

Supporting Information

High-temperature ternary Cu-Si-Al alloy as a core-shell microencapsulated phase change material: Fabrication via dry synthesis method and its thermal stability mechanism

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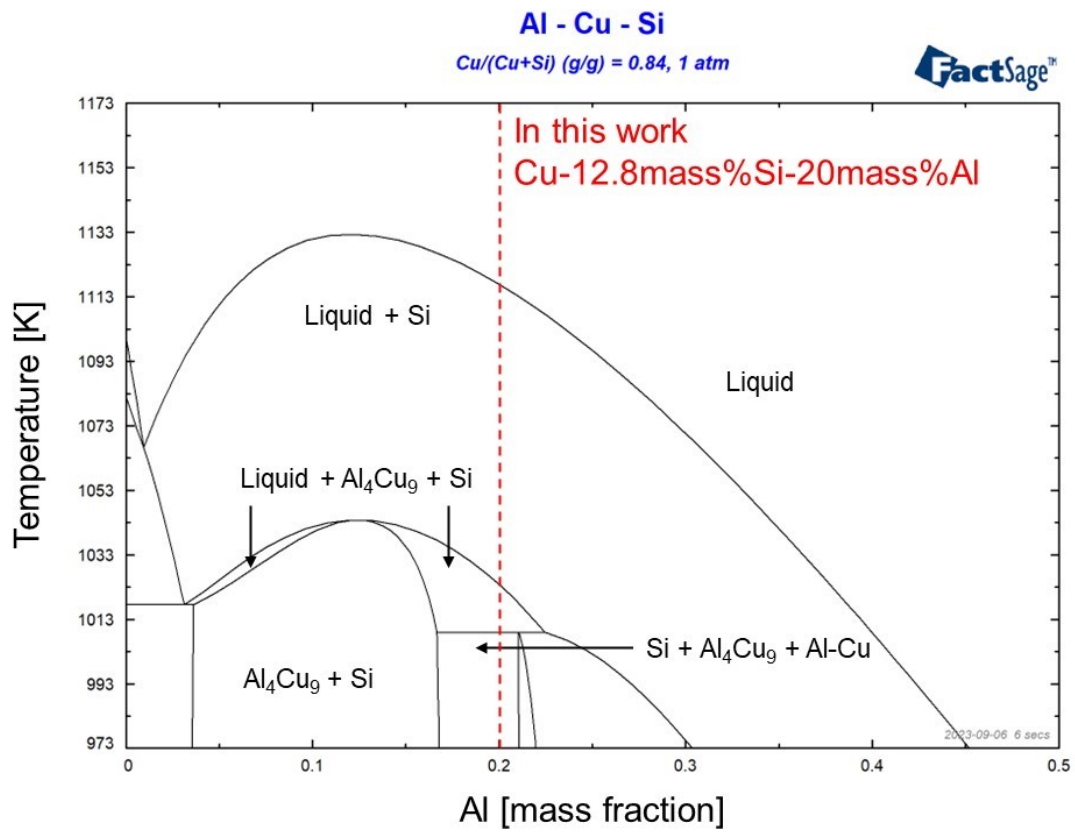


Figure S1. Cu-Si-Al based alloy phase diagram calculated by FactSage 8.2.

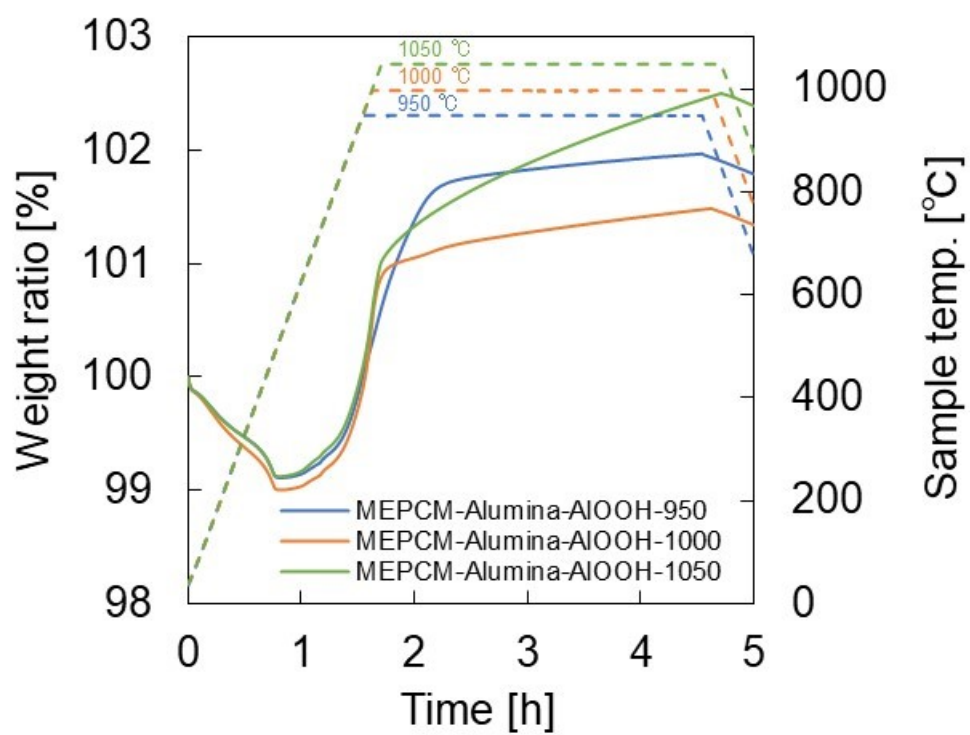


Figure S2. Thermogravimetric (TG) curves during heat-oxidation treatment of MEPCM-Alumina-AIOOH at 950 °C, 1000 °C, and 1050 °C for three hours in an O₂ environment.

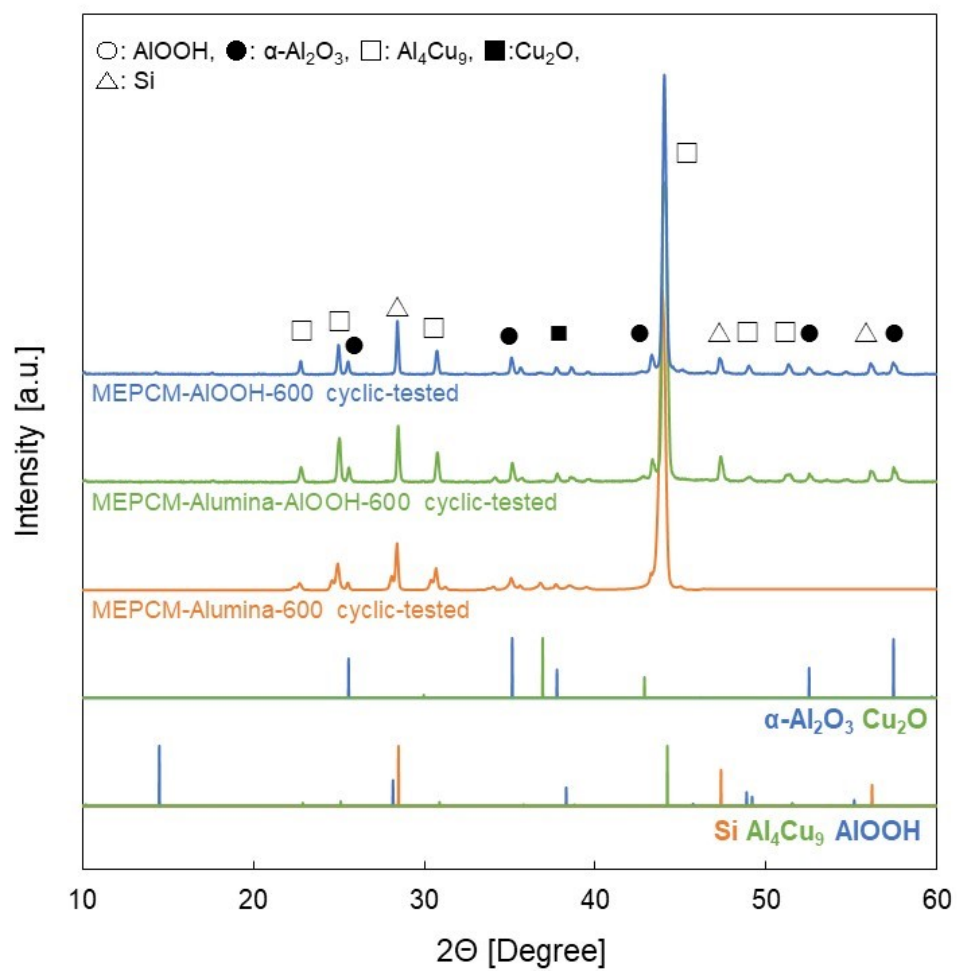


Figure S3. X-ray diffraction (XRD) patterns of MEPCM after 600 cyclic tests.

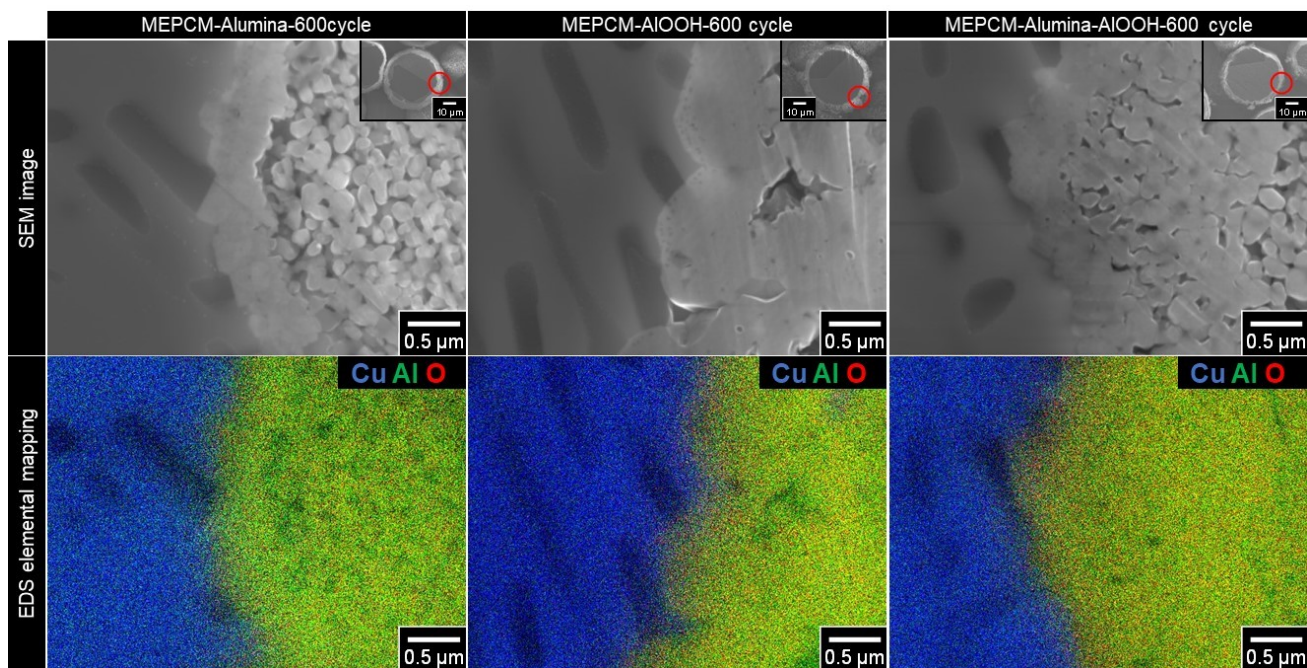


Figure S4. SEM images and EDS elemental mapping after 600 cyclic tests.

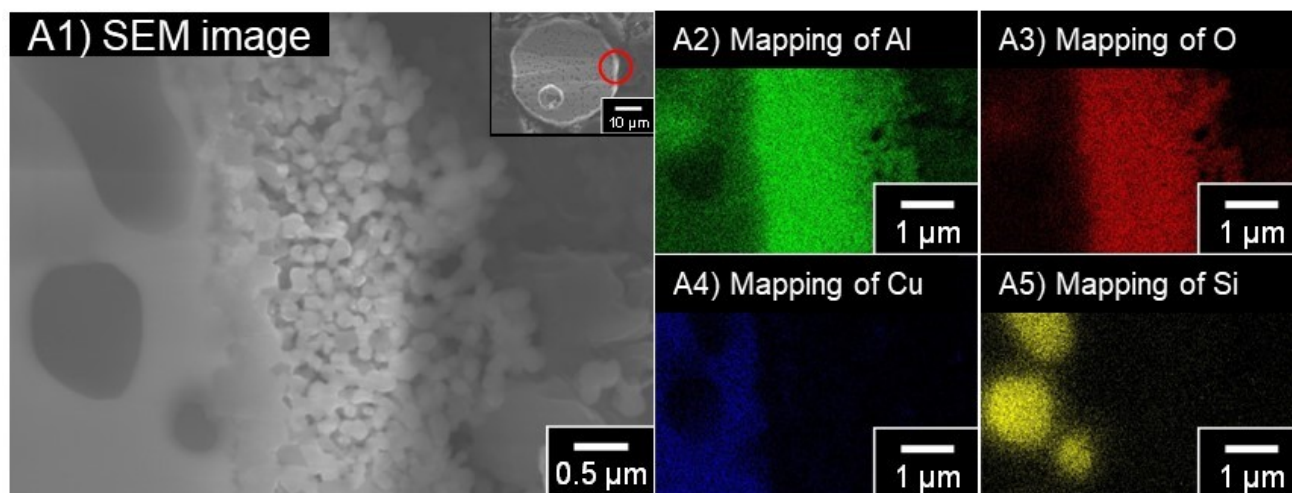


Figure S5. EDS elemental mapping of the cross-section of MEPCM-Alumina.

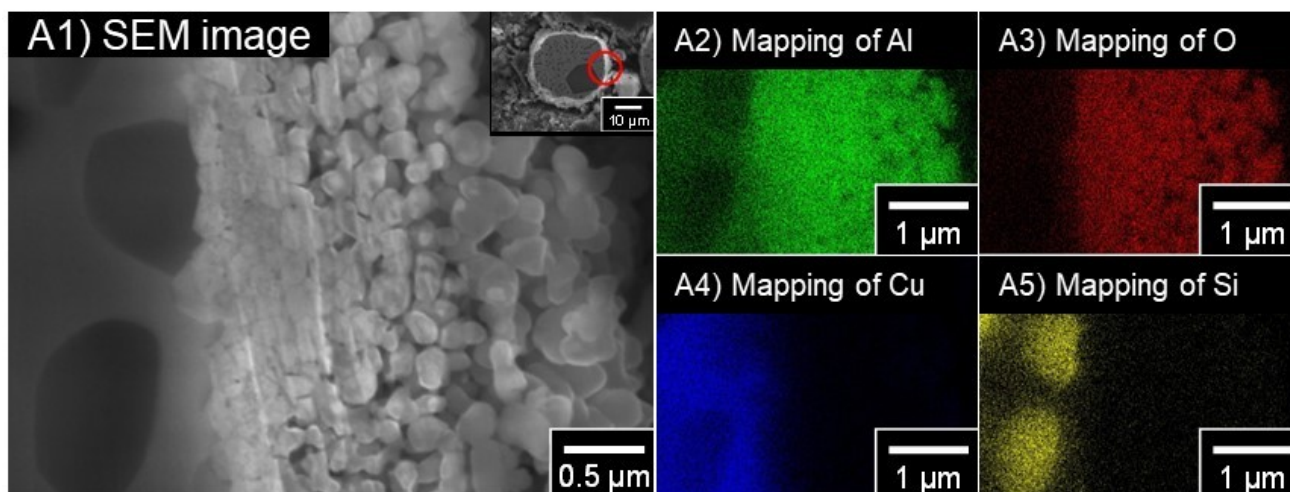


Figure S6. EDS elemental mapping of the cross-section of MEPCM-Alumina-AlOOH.

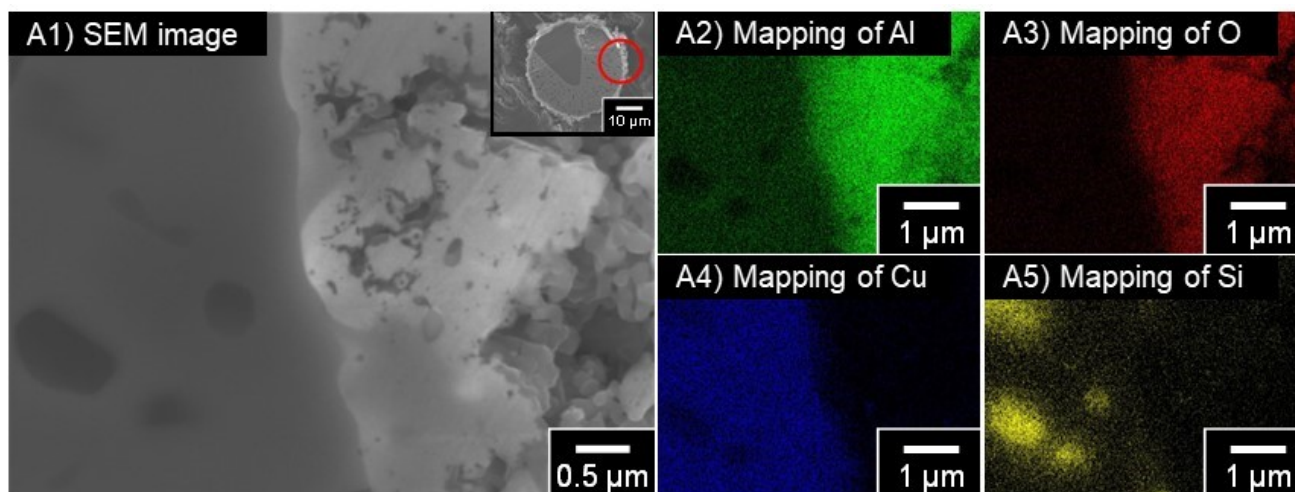


Figure S7. EDS elemental mapping of the cross-section of MEPCM-AlOOH.